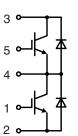


# High Voltage IGBT Phase-Leg

# FII24N170AH1

**Characteristic Values** 



 $egin{array}{lll} V_{\text{CES}} &=& 1700V \\ I_{\text{C25}} &=& 18A \\ V_{\text{CE(sat)}} &\leq& 6V \\ t_{\text{fi(typ)}} &=& 45 \text{ns} \end{array}$ 

ISOPLUS i4-PAC™

# (Electrically Isolated Tab)

Symbol	Test Conditions	Maximum Ratings		
V <sub>CES</sub>	$T_J = 25^{\circ}C \text{ to } 150^{\circ}C$	1700 V		
V <sub>GES</sub>	Continuous	± 20 V		
$V_{GEM}$	Transient	± 30 V		
C25 C90 F25 F90	$T_{c} = 25^{\circ}C$ $T_{c} = 90^{\circ}C$ $T_{c} = 25^{\circ}C$ $T_{c} = 90^{\circ}C$ $T_{c} = 25^{\circ}C$	18 A 11 A 24 A 14 A 75 A		
SSOA (RBSOA)	$V_{\rm GE} = 15 {\rm V},  {\rm T}_{\rm VJ} = 125 {\rm ^{\circ}C},  {\rm R}_{\rm G} = 5 \Omega$ Clamped Inductive Load	$I_{\text{CM}} = 50 \qquad A$ $V_{\text{CES}} \le 1360 \qquad V$		
P <sub>c</sub>	T <sub>c</sub> = 25°C	140 W		

# Symbol Test Conditions

(T <sub>J</sub> = 25°C Unless Otherwise Specified) Min.	Тур.	Max	ζ.
$V_{GE(th)}$ $I_{C} = 250 \mu A, V_{CE} = V_{GE}$ 3.0		5.0	V
$I_{CES}$ $V_{CE} = 0.8 \cdot V_{CES}, V_{GE} = 0V$ Note 2, $T_J = 125^{\circ}C$		100 1.5	μA mA
$I_{\text{GES}}$ $V_{\text{CE}} = 0\text{V}, V_{\text{GE}} = \pm 20\text{V}$		±100	nA
$V_{CE(sat)}$ $I_{C} = 16A, V_{GE} = 15V, Note 1$ $T_{J} = 125^{\circ}C$	4.5 4.8	6.0	V
t <sub>d(on)</sub> Inductive load, T <sub>u</sub> = 25°C	48		ns
$I_c = 24A, V_{GE} = 15V$	60		ns
$t_{d(off)}$ $V_{CE} = 600V, R_g = 39\Omega$	200		ns
t <sub>fi</sub> Note 2	45		ns
E <sub>off</sub>	1.1		mJ
t <sub>d(on)</sub>	40		ns
t Inductive load, T <sub>J</sub> = 125°C	60		ns
$I_{\rm c} = 24A, V_{\rm GE} = 15V$	2.5		mJ
$t_{d(off)}$ $V_{CE} = 600V, R_{G} = 39\Omega$	220		ns
t <sub>fi</sub> Note 2	55		ns
E <sub>off</sub>	1.7		mJ

## Features

- NPT<sup>3</sup> IGBT
- Low Saturation Voltage
- Positive Temperature Coefficient for Easy Paralleling
- Fast Switching
- Short Tail Current for Optimized Performance in Resonant Circuits
- SONIC-FRD™ Diode
  - Fast Reverse Recovery
  - Low Operating Forward Voltage
  - Low Leakage Current
- ISOPLUS i4-PAC™ Package
- Isolated Back Surface
- Low Coupling Capacity Between Pins and Heatsink
- Enlarged Creepage Towards Heatsink
- Application Friendly Pinout
- low inductive current path
- High Reliability
- Industry Standard Outline
- UL registered, E 72873

# **Applications**

- Single PhaseLeg
- Buck-Boost Chopper
- H-bridge
- Power Supplies
- Induction Heating
- Four Quadrant DC Drives
- Controlled Rectifier
- Three Phase Bridge
- AC Drives
- Controlled Rectifier





Symbol Test ConditionsChara $(T_J = 25^{\circ}\text{C Unless Otherwise Specified})$ Min.		cteristic Values Typ.   Max.		
g <sub>fs</sub>	$I_{\rm C} = 24A, V_{\rm CE} = 10V, Note 1$	10	16	S
C <sub>ies</sub>			2400	pF
C <sub>oes</sub>	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$		150	pF
C <sub>res</sub>			30	pF
$Q_{g(on)}$			105	nC
Q <sub>ge</sub>	$I_{c} = 16A, V_{ge} = 15V, V_{ce} = 0.5 \cdot V_{ces}$		17	nC
Q <sub>gc</sub>			30	nC
R <sub>thJC</sub>				0.90 °C/W
R <sub>thCS</sub>			0.6	°C/W

# Reverse Sonic Diode (FRD)

<b>Symbol Test Conditions</b> (T <sub>J</sub> = 25°C Unless Otherwise Specified)	Char Min.	Characteristic Values Min.   Typ.   Max.			
$V_F$ $I_F = 20A, V_{GE} = 0V, Note 1$	T <sub>J</sub> = 125°C	2.50 2.50	2.95 V		
$ \begin{cases} I_{RM} \\ t_{rr} \end{cases}                                  $	T <sub>J</sub> = 125°C	23 230	Ans		
R <sub>thJC</sub> R <sub>thCS</sub>		1.6 0.6	°C/W		

#### ISOPLUS i4-PAC™ OutLine MILLIMETERS MAX MAX 3.00 .045 1.14 .058 1.47 .029 0.74 20.80 3.81 .780 .840 19.81 2.11 5.33 .083 .210 .244 6.20 .100 .180 4.57 .660 16.76 .590 .620 14.99 15.75 1.65 2.03

### Component

Symbol	Test Conditions		Maximum F	Maximum Ratings	
T <sub>J</sub>			- 55 +150	°C	
$T_{stg}$			- 55 +150	°C	
F <sub>c</sub>	Mounting Force		20120 / 4.527	N/lb.	
V <sub>ISOL</sub>	50/60Hz, 1 Second		2500	V~	

Symbol Test Conditions		Characteristic Values			
		Min.	Тур.	Max.	
C <sub>p</sub>	Coupling Capacity Between Shorted Pins and Mounting Tab in the Case		40	pF	
d <sub>s</sub> ,d <sub>A</sub> d <sub>s</sub> ,d <sub>A</sub>	Pin - Pin Pin - Backside Metal	1.7 5.5		mm mm	
Weight			6	g	

#### Notes:

- 1. Pulse test,  $t \le 300\mu s$ , duty cycle,  $d \le 2\%$ .
- 2. Switching times & energy losses may increase for higher  $V_{\rm CE}({\rm clamp}),\,T_{\rm J}\,{\rm or}\,R_{\rm g}.$

#### PRELIMANARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

 $\ensuremath{\mathsf{IXYS}}$  Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered 4.835.592 4,931,844 5.049.961 5.237.481 6.162.665 6,404,065 B1 7.005.734 B2 7,157,338B2 6.683.344 by one or more of the following U.S. patents: 4,860,072 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 5,017,508 5,063,307 7,063,975 B2 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537